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| TO : | 文件编号 | HXA-L50-20(01) |
| | 发行日期 | 2019年10月15日 |

承认规格书

种 类： SMD Power Choke Coil

系列号： HXPC0515H-1R0M

客户料号： _____

| | |
|-------|-------------|
| 客户承认栏 | |
| | |
| 承认日期 | 年 月 日 |

(贵司承认后请签署一份返回艾申迪电子, 谢谢!)

厦门艾申迪电子科技有限公司技术质量部

| | | |
|-----|-----|-----|
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SMD Power Choke Coil

HXPC0515H-1R0M

ECN HISTORY LIST

| REV | DATE | DESCRIPTION | APPROVED | CHECKED | DRAWN |
|--------|----------|-------------|----------|---------|-------|
| 1.0 | 19/10/15 | 新發行 | 龙梅 | 梁峰 | 王亮 |
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| 備 注 | | | | | |

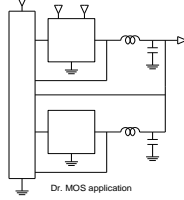
1. Features

1. Shielded construction.
2. Capable of corresponding high frequency .
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.

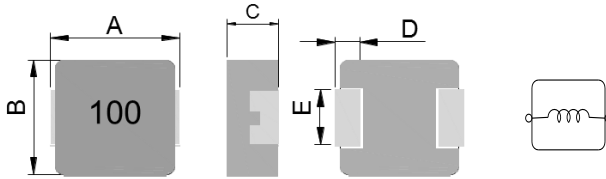


2. Applications

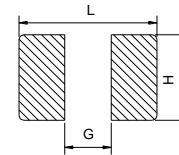
Note PC power system · incl. IMVP-6
DC/DC converter .



3. Dimensions



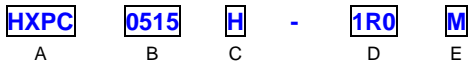
Recommend PC Board Pattern



| Series | A(mm) | B(mm) | C(mm) | D(mm) | E(mm) |
|-----------|----------|---------|---------|---------|---------|
| HXPC0515H | 5.4±0.35 | 5.2±0.2 | 1.2±0.2 | 1.2±0.2 | 2.2±0.3 |

| L(mm) | G(mm) | H(mm) |
|-------|-------|-------|
| 6.0 | 2.2 | 2.5 |

4. Part Numbering



- A: Series
- B: Dimension
- C: Type
- D: Inductance
- E: Inductance Tolerance
- AxC
- Magnetic metal powder
- 1R0=1.0uH
- M=±20%

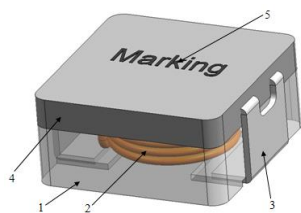
5. Specification

| ISND Part Number | Inductance L0 (uH)±20% @ 0 A | I sat (A) Typ. | I rms (A) Typ. | DCR(mΩ) Max. @25°C |
|------------------|------------------------------|----------------|----------------|--------------------|
| HXPC0515H-1R0M | 1.0 | 9 | 6.5 | 23 |

Note:

1. Test frequency : L : 100KHz /1.0V;
2. All test data referenced to 25°C ambient.
3. Testing Instrument : L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately Δt of 40°C (keep 1min.).
5. Saturation Current (Isat) will cause L0 to drop 30% typical. (keep quickly).
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design ,component, PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Pa

6. Material List



| NO | Items | Materials |
|----|----------------|-------------------------------|
| 1 | Core | Alloy Powder |
| 2 | Wire | Polyester Wire or equivalent. |
| 3 | Solder Plating | 100% Pb free solder |
| 4 | paint | Epoxy resin |
| 5 | Ink | Halogen-free ketone |

7. Reliability and Test Condition

| Item | Performance | Test Condition |
|--|--|---|
| Operating temperature | -55~+125°C | |
| Storage temperature and Humidity range | -55~+125°C ,50~60%RH (Product without taping) | |
| Electrical Performance Test | | |
| Inductance | Refer to standard electrical characteristics list. | HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter. |
| DCR | | CH16502,Agilent33420A Micro-Ohm Meter. |
| Saturation Current (Isat) | △L20% typical. | Saturation DC Current (Isat) will cause L0 to drop △L(%) (keep quickly). |
| Heat Rated Current (Irms) | Approximately $\Delta T \leq 40^\circ\text{C}$ | Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T(^\circ\text{C})$ without core loss. 1. Applied the allowed DC current (keep 1 min.). 2. Temperature measured by digital surface thermometer |
| Reliability Test | | |
| High Temperature Exposure Test | Electric specifications should be satisfied | Temperature: $125 \pm 2^\circ\text{C}$. Duration: 1000 ± 12 hrs. Measured at room temperature after placing for 2 to 3 hrs. (MIL-PRF-27) |
| Biased Humidity Test | | Humidity: $85 \pm 3\%$ RH. Temperature: $85 \pm 2^\circ\text{C}$. Duration: 1000 ± 12 hrs. Measured at room temperature after placing for 2 to 3 hrs (AEC-Q200-REV C) |
| Thermal shock test | | Condition for 1 cycle Step1: $-40 + 0 / -2^\circ\text{C}$ 15±1 min. Step2: Room temperature within ≤ 0.2 min. Step3: $+125 + 2 / -0^\circ\text{C}$ 15±1 min. Number of cycles: 300 Measured at room temperature after placing for 2 to 3 hrs. (AEC-Q200-REV C) |
| Vibration test | | Frequency: 10-2000-10Hz for 20 min. Amplitude: Parts mounted within 2" from any secure point. Directions and times: X, Y, Z directions for 20 min. This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 12 hours). (MIL-STD-202 Method 204 D Test condition B) |
| Reflow test | | Pre-heat : $150 \pm 5^\circ\text{C}$ Duration : 5 minutes Temperature : $260 \pm 5^\circ\text{C}$, 20~40 seconds (IPC/JEDEC J-STD-020C) |
| Solder test | | Terminals should be covered by over 95% solder on visual inspection |

8. Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

(2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

(3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4-5sec.

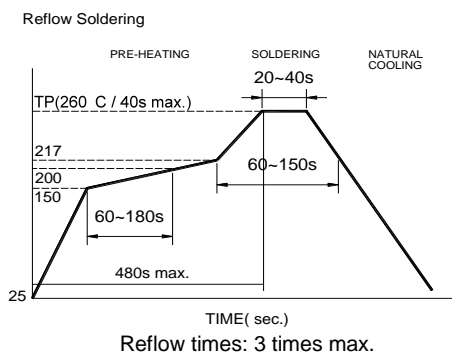


Fig.1

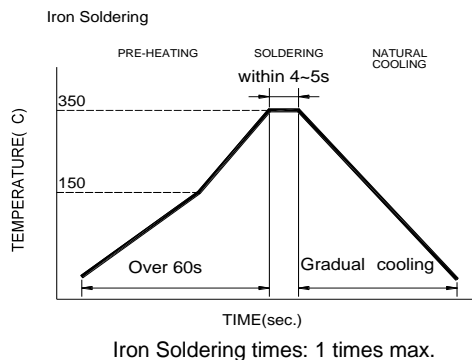
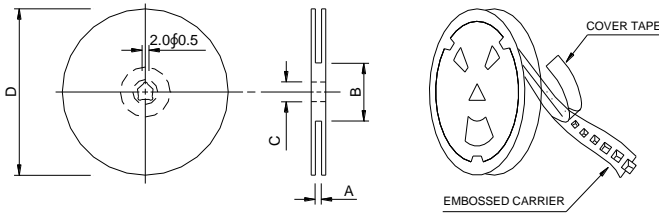


Fig.2

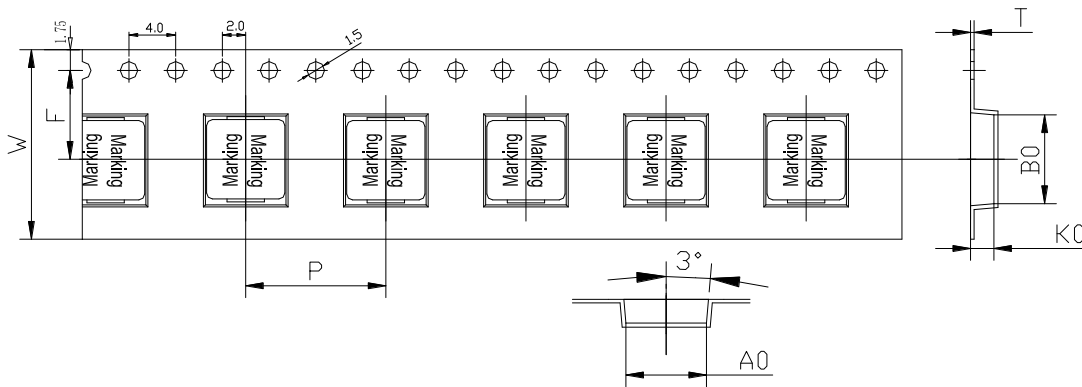
9. Packaging Information

(1) Reel Dimension



| Type | A(mm) | B(mm) | C(mm) | D(mm) |
|----------|----------|-------|----------|-------|
| 13"x12mm | 12.0±0.5 | 100±2 | 13.5±0.5 | 330 |

(2) Tape Dimension

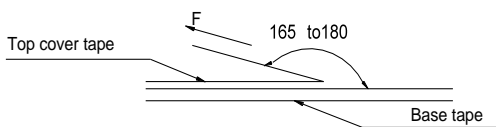


| Series | Size | Bo(mm) | Ao(mm) | Ko(mm) | P(mm) | W(mm) | F(mm) | t(mm) |
|--------|------|---------|---------|---------|---------|--------|---------|-----------|
| HXPC | 0515 | 6.9±0.1 | 5.5±0.1 | 1.7±0.1 | 8.0±0.1 | 12±0.3 | 5.5±0.1 | 0.35±0.05 |

(3) Packaging Quantity

| HXPC | 0518 |
|-------------|------|
| Chip / Reel | 3000 |

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 stadnard).

| Room Temp. (°C) | Room Humidity (%) | Room atm (hPa) | Tearing Speed mm/min |
|-----------------|-------------------|----------------|----------------------|
| 5~35 | 45~85 | 860~1060 | 300 |

Application Notice

- Storage Conditions
 - To maintain the solderability of terminal electrodes:
 - ISND products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
 - Temperature and humidity conditions: Less than 30°C and 70% RH.
 - Recommended products should be used within 6 months form the time of delivery.
 - The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

单击下面可查看定价，库存，交付和生命周期等信息

[>>ISND\(华信安\)](#)